



60V +175°C N-CHANNEL ENHANCEMENT MODE MOSFET PowerDI5060-8

Product Summary

| BV _{DSS} | R _{DS(ON)} | I _D T _C = +25°C (Note 9) |
|-------------------|---------------------------------------|--|
| 60V | $6.5 \text{m}\Omega$ @ $V_{GS} = 10V$ | 100A |
| | $10m\Omega$ @ $V_{GS} = 4.5V$ | 81.6A |

Description and Applications

This MOSFET is designed to meet the stringent requirements of Automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

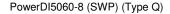
- Engine Management Systems
- Body Control Electronics
- DC-DC Converters

Features

- Rated to +175°C —Ideal for High Ambient Temperature Environments
- 100% Unclamped Inductive Switching (UIS) Test in Production— Ensures More Reliable and Robust End Application
- Low R_{DS(ON)}—Minimizes On State Losses
- Low Input Capacitance
- Fast Switching Speed
- Wettable Flank for Improved Optical Inspection
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- The DMTH6006LPSWQ is suitable for automotive applications requiring specific change control and is AEC-Q101 qualified, is PPAP capable, and is manufactured in IATF16949:2016 certified facilities.

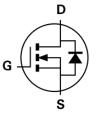
Mechanical Data

- Case: PowerDI[®]5060-8
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Finish Matte Tin Annealed over Copper Leadframe; Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.097 grams (Approximate)

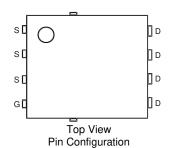




Top View Bottom View



Internal Schematic



Ordering Information (Note 4)

| _ | | | |
|---|------------------|------------------------------|------------------|
| | Part Number | Case | Packaging |
| | DMTH6006LPSWQ-13 | PowerDI5060-8 (SWP) (Type Q) | 2500/Tape & Reel |

Notes

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



Oll = Manufacturer's Marking TH6006LSW = Product Type Marking Code YYWW = Date Code Marking YY = Last Two Digits of Year (ex: 19 = 2019) WW = Week Code (01 to 53)

PowerDI is a registered trademark of Diodes Incorporated.



Maximum Ratings (@ $T_A = +25$ °C, unless otherwise specified.)

| Characteristic | | Symbol | Value | Unit |
|---|---|------------------|--------------|------|
| Drain-Source Voltage | | V _{DSS} | 60 | V |
| Gate-Source Voltage | | V _{GSS} | ±20 | V |
| Continuous Drain Current, V _{GS} = 10V (Note 5) | $T_A = +25^{\circ}C$ $T_A = +100^{\circ}C$ | I _D | 17.2 12.1 | А |
| Continuous Drain Current, $V_{GS} = 10V$ (Notes 6 & 9) $T_C = +25^{\circ}C$ $T_C = +100^{\circ}C$ | | I _D | 100 71.6 | Α |
| Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%) | I _{DM} | 400 | Α | |
| Maximum Continuous Body Diode Forward Current (Note 6) | I _S | 100 | Α | |
| Pulsed Body Diode Forward Current (10µs Pulse, Duty Cycle | I _{SM} | 400 | Α | |
| Avalanche Current, L=0.1mH | | I _{AS} | 28.5 | Α |
| Avalanche Energy, L=0.1mH | | E _{AS} | 40.7 | mJ |

Thermal Characteristics

| Characteristic | | Symbol | Value | Unit |
|--|----------------------|------------------|-------------|------|
| Total Power Dissipation (Note 5) | $T_A = +25$ °C | P_{D} | 2.88 | W |
| Thermal Resistance, Junction to Ambient (Note 5) | | $R_{\Theta JA}$ | 52 | °C/W |
| Total Power Dissipation (Note 6) | $T_C = +25^{\circ}C$ | P_{D} | 100 | W |
| Thermal Resistance, Junction to Case (Note 6) | | R _{eJC} | 1.5 | °C/W |
| Operating and Storage Temperature Range | | $T_{J_1}T_{STG}$ | -55 to +175 | °C |

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

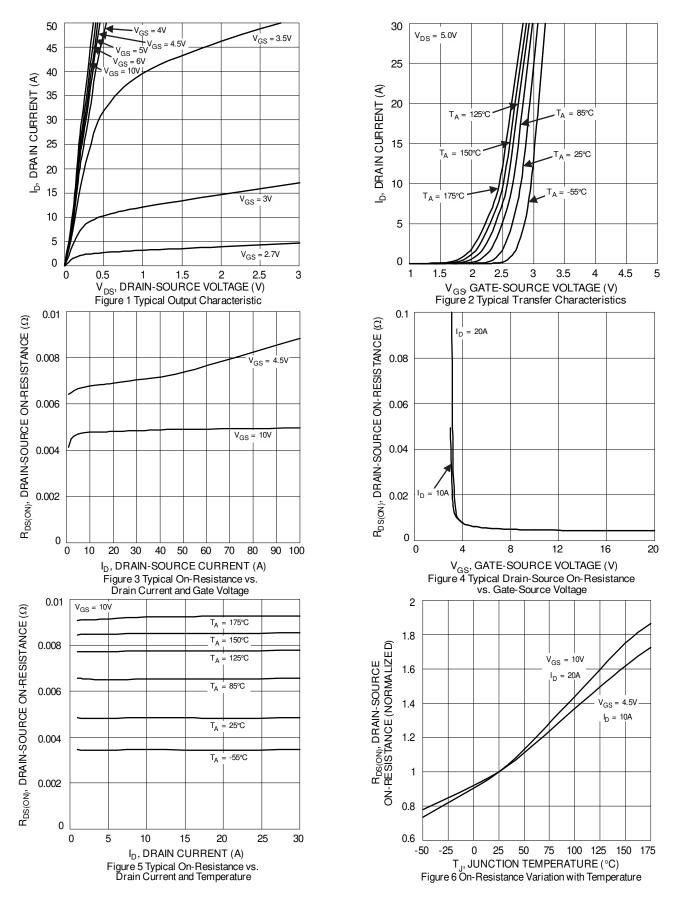
| Characteristic | Symbol | Min | Тур | Max | Unit | Test Condition | |
|--|---------------------|-----|------|------|-------|--|--|
| OFF CHARACTERISTICS (Note 7) | | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | 60 | _ | _ | V | $V_{GS} = 0V$, $I_D = 1mA$ | |
| Zero Gate Voltage Drain Current | I _{DSS} | 1 | _ | 1 | μΑ | $V_{DS} = 48V, V_{GS} = 0V$ | |
| Gate-Source Leakage | I _{GSS} | _ | _ | ±100 | nA | $V_{GS} = \pm 20V, V_{DS} = 0V$ | |
| ON CHARACTERISTICS (Note 7) | | | | | | | |
| Gate Threshold Voltage | $V_{GS(TH)}$ | 1.2 | | 2.5 | V | $V_{DS} = V_{GS}$, $I_D = 250\mu A$ | |
| Static Drain-Source On-Resistance | - | _ | 4.9 | 6.5 | mΩ | $V_{GS} = 10V, I_D = 20A$ | |
| Static Drain-Source On-Nesistance | R _{DS(ON)} | _ | 7.1 | 10 | 11122 | $V_{GS} = 4.5V, I_D = 10A$ | |
| Diode Forward Voltage | V_{SD} | _ | 0.8 | 1.2 | V | V _{GS} = 0V, I _S = 20A | |
| DYNAMIC CHARACTERISTICS (Note 8) | | | | | | • | |
| Input Capacitance | Ciss | | 2162 | | | $V_{DS} = 30V$, $V_{GS} = 0V$, $f = 1MHz$ | |
| Output Capacitance | Coss | | 761 | | рF | | |
| Reverse Transfer Capacitance | C_{rss} | | 58 | | | | |
| Gate Resistance | R_g | _ | 0.7 | _ | Ω | $V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$ | |
| Total Gate Charge (V _{GS} = 4.5V) | Qg | _ | 18.1 | _ | | | |
| Total Gate Charge (V _{GS} = 10V) | Q_g | _ | 34.9 | _ | nC | $V_{DS} = 30V, I_{D} = 20A$ | |
| Gate-Source Charge | Q_{gs} | _ | 6.1 | _ | 110 | | |
| Gate-Drain Charge | Q_{gd} | | 7.3 | | | | |
| Turn-On Delay Time | t _{D(ON)} | | 6.0 | _ | | $V_{DD} = 30V, V_{GS} = 10V,$ $I_D = 20A, R_g = 3\Omega$ | |
| Turn-On Rise Time | t _R | _ | 5.4 | _ | ns | | |
| Turn-Off Delay Time | t _{D(OFF)} | _ | 20.4 | _ | 115 | | |
| Turn-Off Fall Time | t _F | _ | 7.8 | _ | | | |
| Body Diode Reverse Recovery Time | t _{RR} | _ | 35.8 | _ | ns | I_ 20A di/dt 100A/us | |
| Body Diode Reverse Recovery Charge | Q _{RR} | _ | 40.2 | | nC | I _F = 20A, di/dt = 100A/μs | |

Notes:

- 5. Device mounted on FR-4 substrate PCB, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.
- 6. Thermal resistance from junction to soldering point (on the exposed drain pad).7. Short duration pulse test used to minimize self-heating effect.
- Guaranteed by design. Not subject to product testing.
 Limited by package.

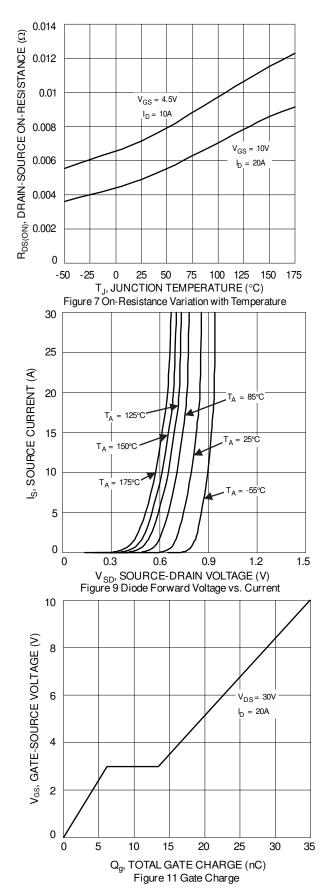


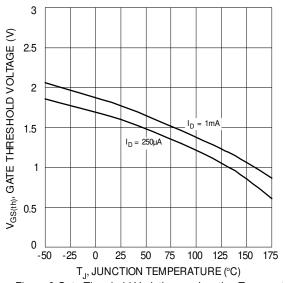


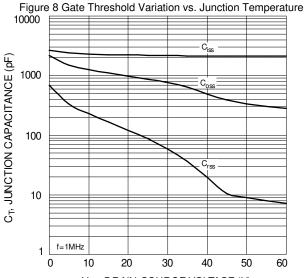


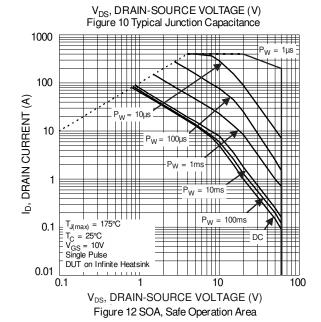




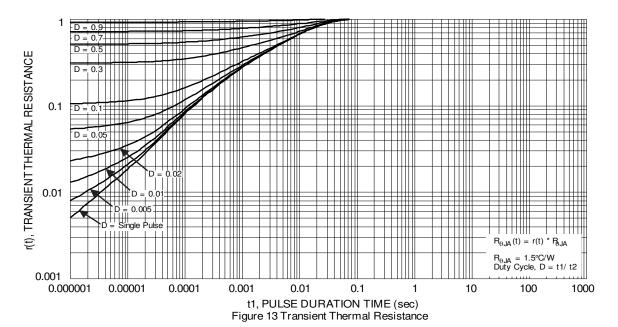














Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

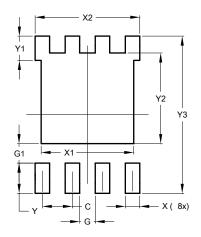
PowerDI5060-8 (SWP) (Type Q) 1.900 Detail A Detail A Detail A Detail A

| PowerDI5060-8 (SWP) (Type Q) | | | | |
|---------------------------------|-----------|---------|-------|--|
| Dim | Min | Max | Тур | |
| Α | 0.90 | 1.10 | 1.00 | |
| A1 | 0 | 0.05 | | |
| b | 0.30 | 0.50 | 0.41 | |
| b2 | 0.20 | 0.35 | 0.25 | |
| b4 | C |).25REF | = | |
| C | 0.230 | 0.330 | 0.277 | |
| D | 5 | .15 BS0 |) | |
| D1 | 4.70 | 5.10 | 4.90 | |
| D2 | 3.56 | 3.96 | 3.76 | |
| D2a | 3.78 4.18 | | 3.98 | |
| Е | 6 | .40 BS0 |) | |
| E1 | 5.60 | 6.00 | 5.80 | |
| E2 | 3.46 | 3.86 | 3.66 | |
| E2a | 4.195 | 4.595 | 4.395 | |
| е | 1 | .27BSC |) | |
| k | 1.05 | | | |
| L | 0.635 | 0.835 | 0.735 | |
| La | 0.635 | 0.835 | 0.735 | |
| L1 | 0.200 | 0.400 | 0.300 | |
| L1a | 0.050REF | | | |
| L4 | 0.025 | 0.225 | 0.125 | |
| М | 3.205 | 4.005 | 3.605 | |
| θ | 10° | 12° | 11° | |
| θ1 | 6° | 8° | 7° | |
| All Dimensions in mm | | | | |

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI5060-8 (SWP) (Type Q)



| Dimensions | Value | | | |
|--------------|---------|--|--|--|
| Dilliensions | (in mm) | | | |
| С | 1.270 | | | |
| G | 0.660 | | | |
| G1 | 0.820 | | | |
| Х | 0.610 | | | |
| X1 | 4.100 | | | |
| X2 | 4.420 | | | |
| Υ | 1.270 | | | |
| Y1 | 1.020 | | | |
| Y2 | 3.810 | | | |
| Y3 | 6.610 | | | |



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